



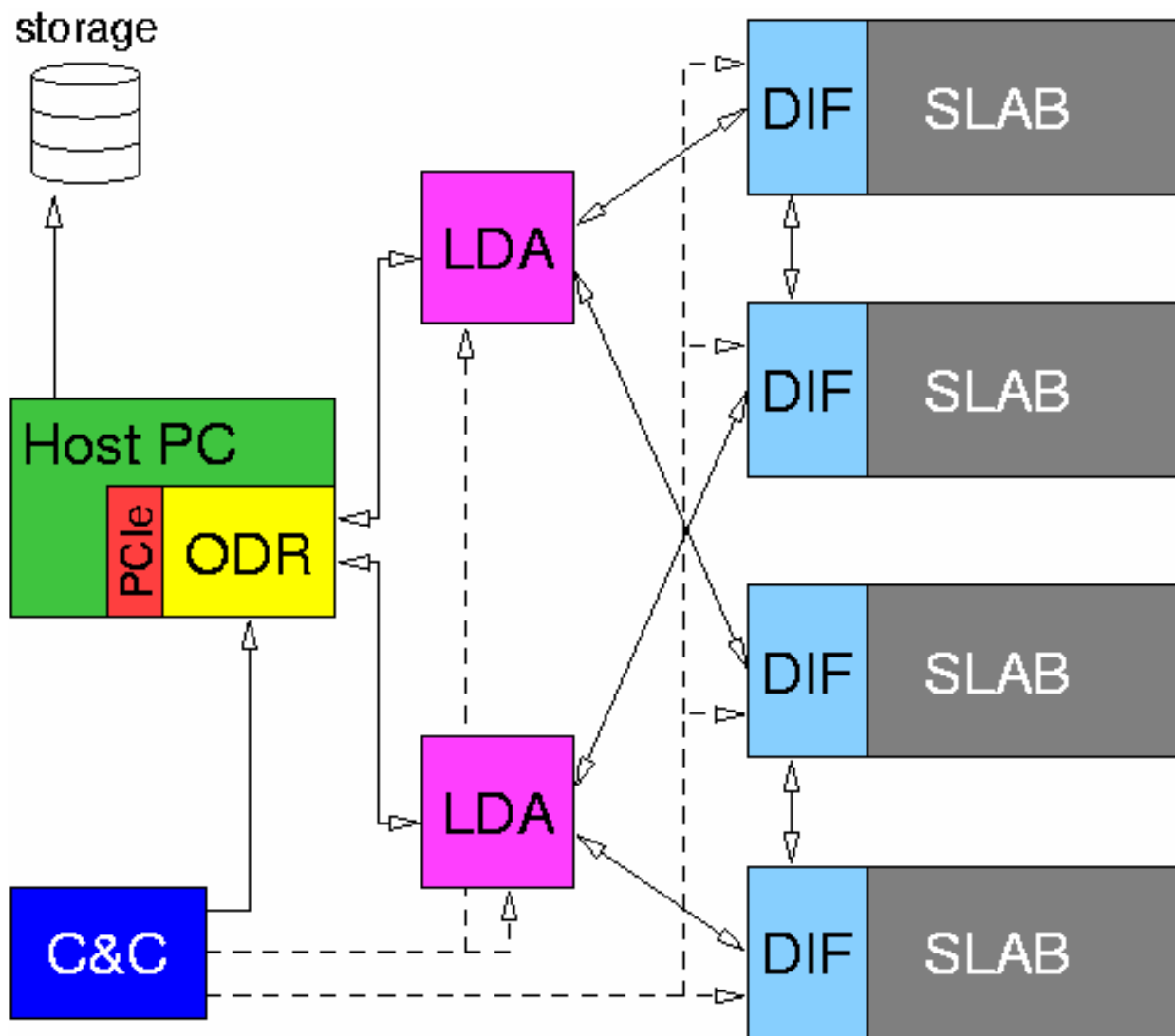
# CALICE DAQ Developments

DAQ overview

DIF functionality and implementation

EUDET Prototype development path

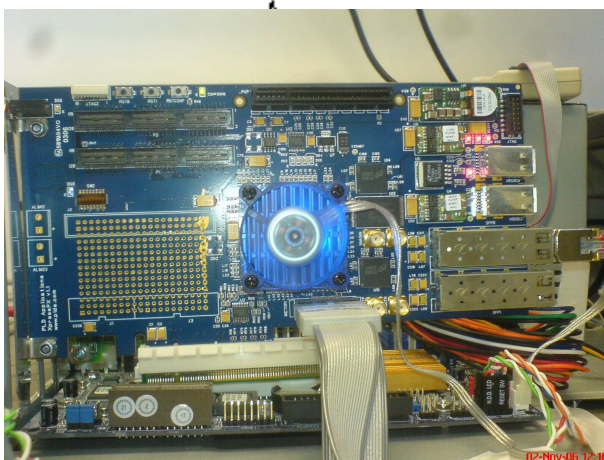
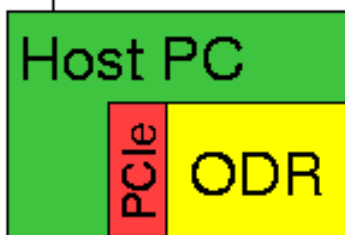
# DAQ architecture



- Slab hosts VFE chips
- DIF connected to Slab
- LDA servicing DIFs
- LDAs read out by ODR
- PC hosts ODR, through PCIeexpress
- C&C routes clock, controls

# ODR and Data Rates

storage



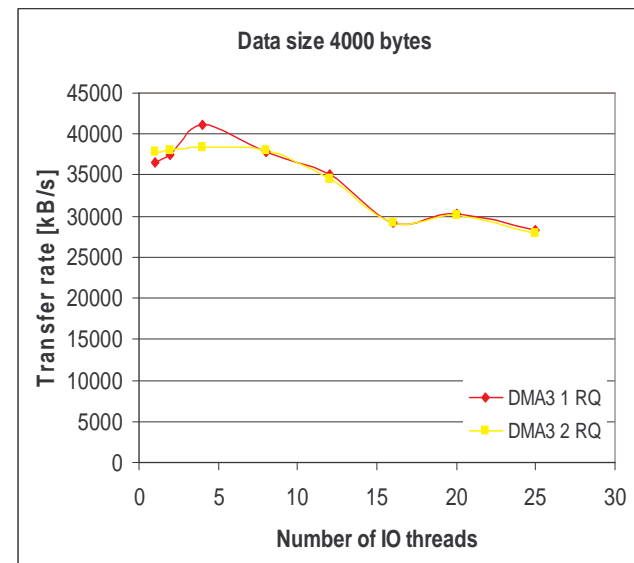
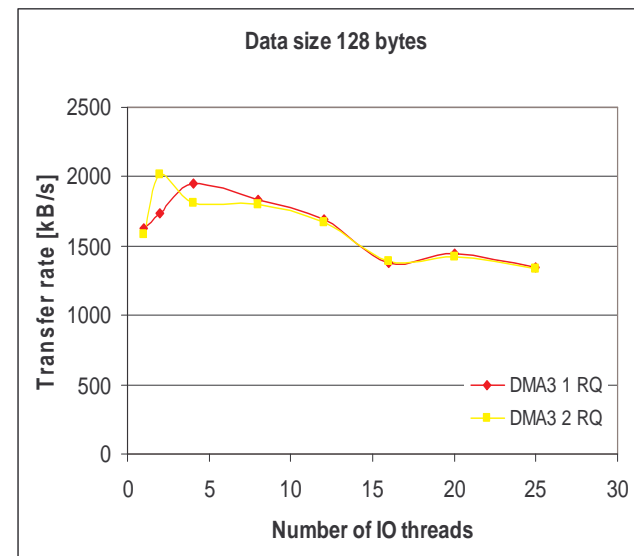
- ODR is a commercial FPGA board with PCIe interface

(Virtex4-FX100, PCIe 8x, etc.)

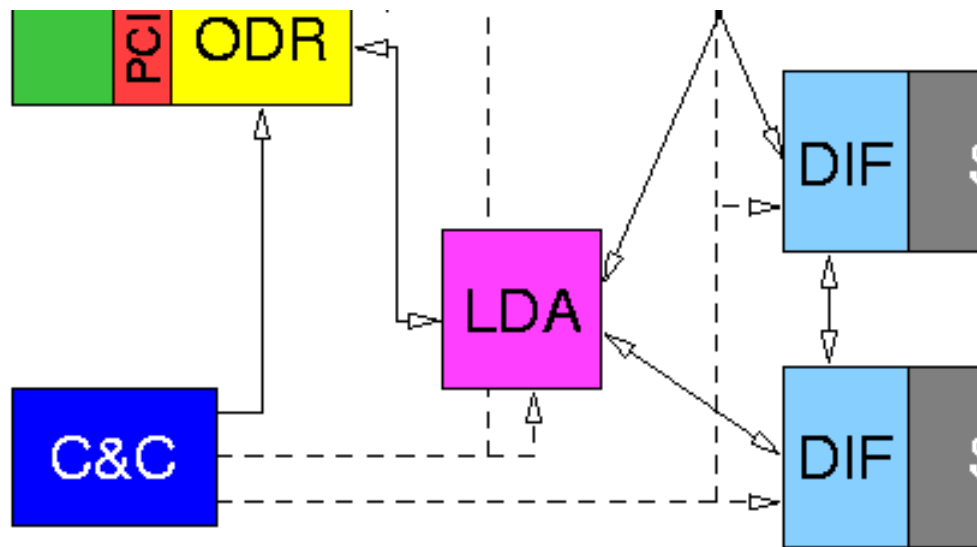
- Customised firm- and software:

DMA driver pulls data off the onboard RAM, writes to disk

- Performance studies & optimisation



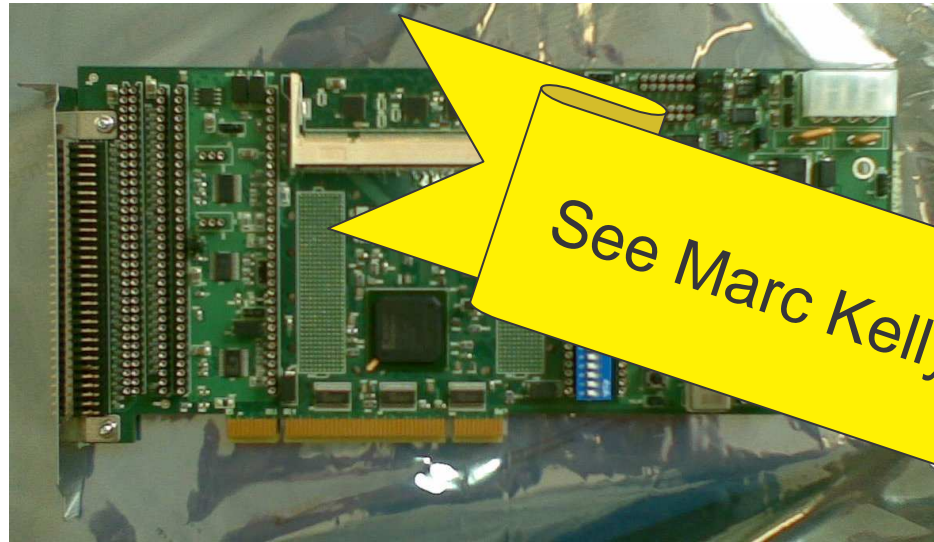
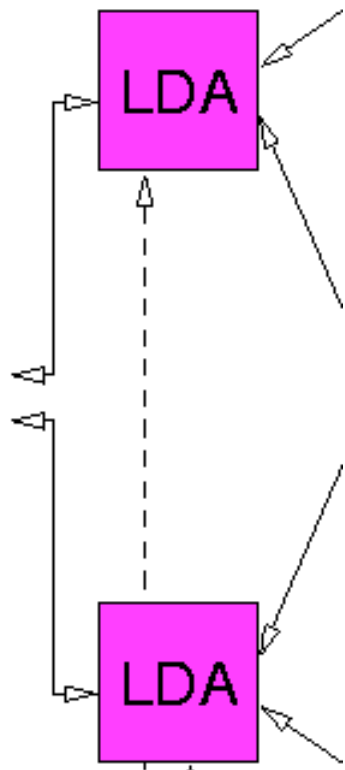
# Clock & Controls Distribution



- C&C unit provides machine clock and fast signals to ODR, LDA (and DIF?)
- Clock jitter requirement seems not outrageous (at the moment)

- Fast Controls: encoded commands on the LDA-DIF link
- Slow Controls/Configuration: transfers on LDA-DIF link
- Low-latency fast signals: distributed 'directly' (if necessary)

# LDA and link to ODR

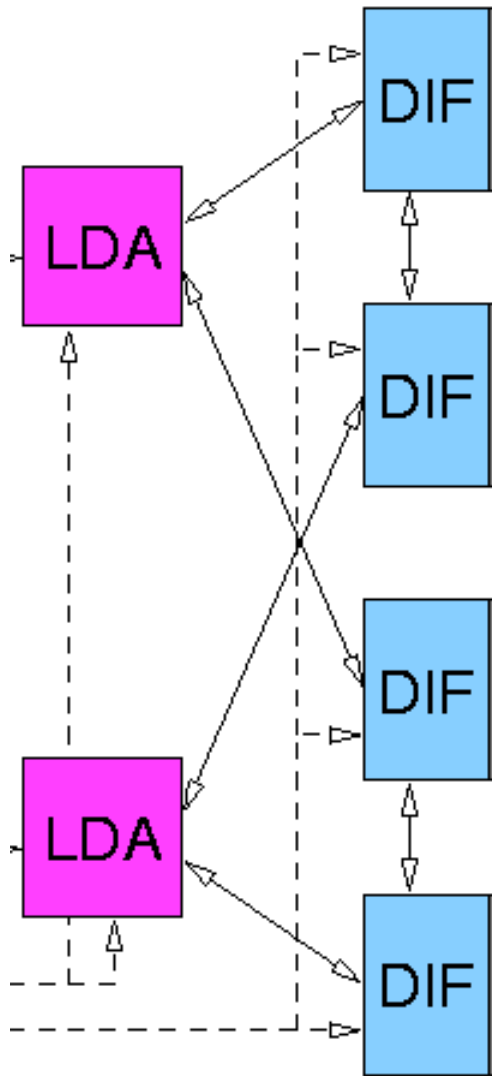


See Marc Kelly's talk

1<sup>st</sup> Prototype is again a commercial FPGA board with customised firmware and hardware add-ons:

- High-bandwidth link to ODR
- Many links towards DIFs

# LDA-DIF link



## LDA-DIF link:

- Serial link running at multiple of machine clock
- 50Mbps (raw) bandwidth minimum
- robust encoding (8B/10B or alike)
- anticipating 8...16 DIFs on an LDA, bandwidth permitting
- LDAs serve even/odd DIFs for redundancy

# LDA-DIF physical interface

	Gnd	2	1	Clk+	Pair1 (STP)	clock
	DL2D+	4	3	Clk-		
Pair2 (STP)	DL2D-	6	5	Gnd	Pair3 (STP)	data
	Gnd	8	7	DD2L+		
	SpD2L+	10	9	DD2L-	Pair4 (STP)	control
	SpD2L-	12	11	Gnd		
	Pow2	14	13	Pow1	Pair5 (UTP)	spare data
	SpL2D-	16	15	SpL2D+		
	Pow3	18	17	Gnd		
			19	Pow4		spare control

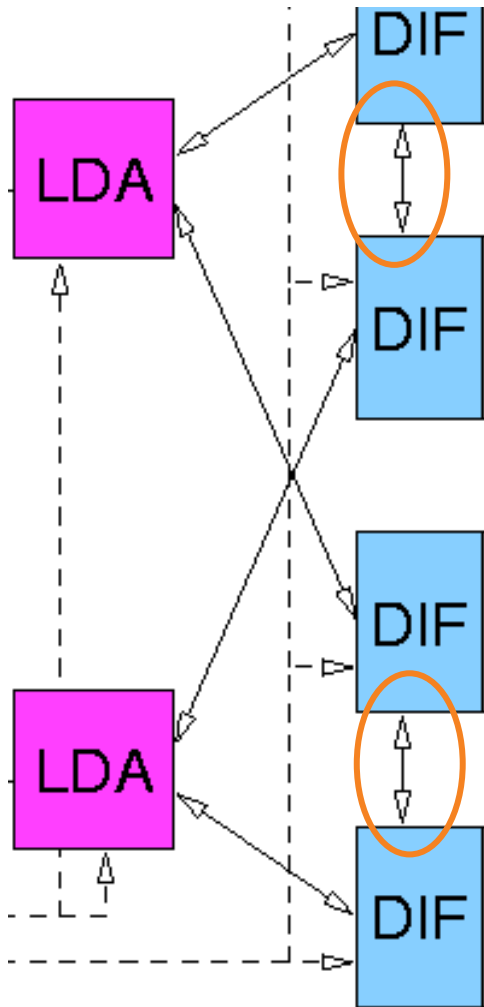
Possible Pinout for HDMI

(Based on SAMTEC HPDPI  
cable signal designation)

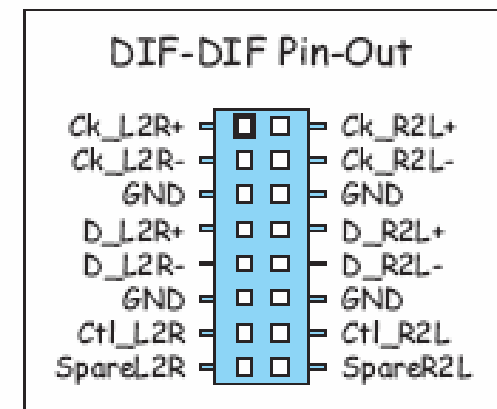
LDA-DIF link physical form factor:

- Differential signals on shielded twisted pairs
- Few single-ended control lines
- HDMI connectors and cabling: commercially available in high quality

# DIF-DIF link



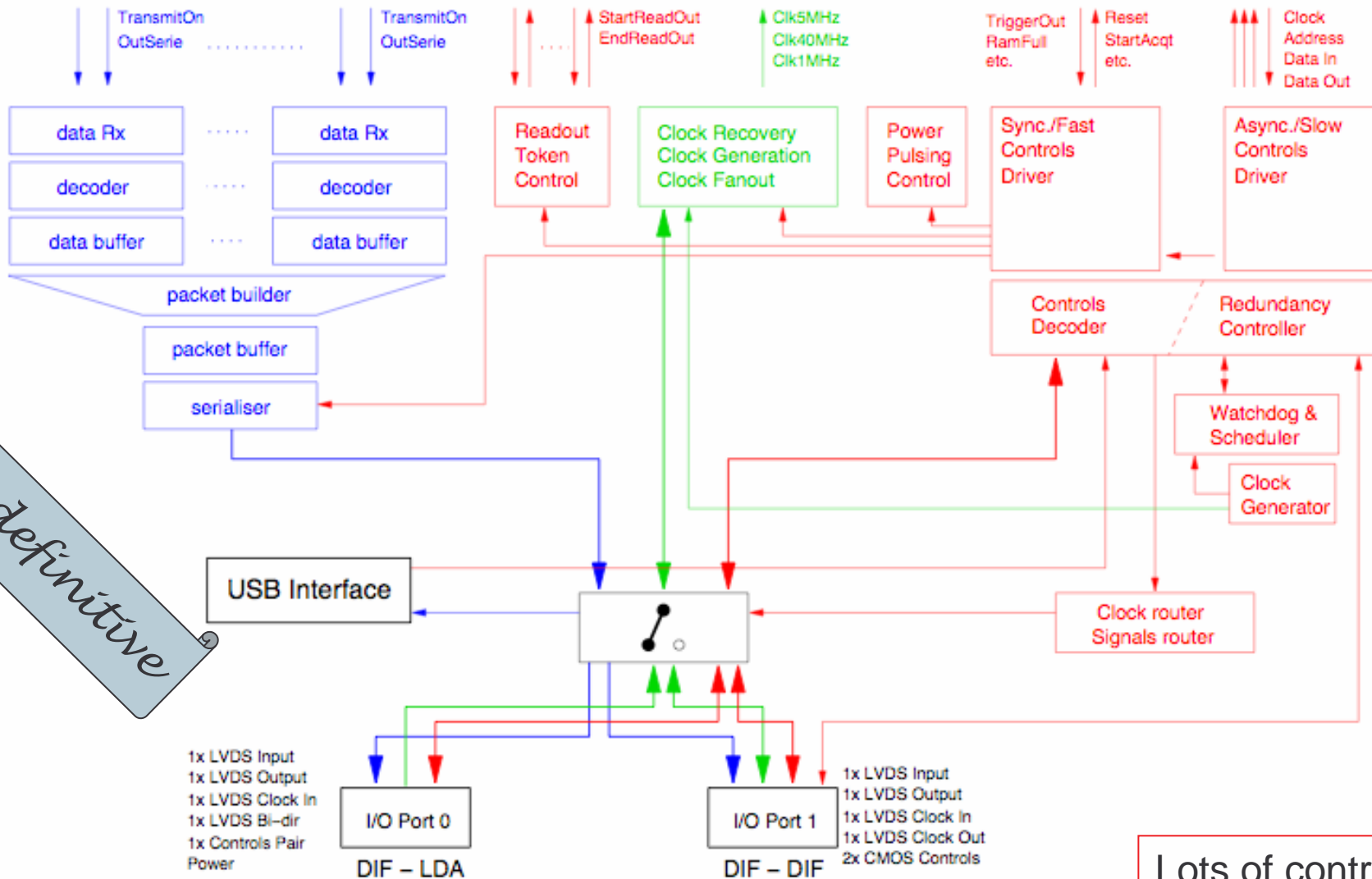
- Redundancy against loss of LDA link
- Provides differential signals:
  - Clock in both directions
  - Data and Control connections
  - Two spares: one each direction
- Plus two single-ended control lines
- Single LDA-DIF link bandwidth sufficiently large for data of two DIFs





# Draft DIF block diagram

SLAB



*not definitive*

Lots of controls....

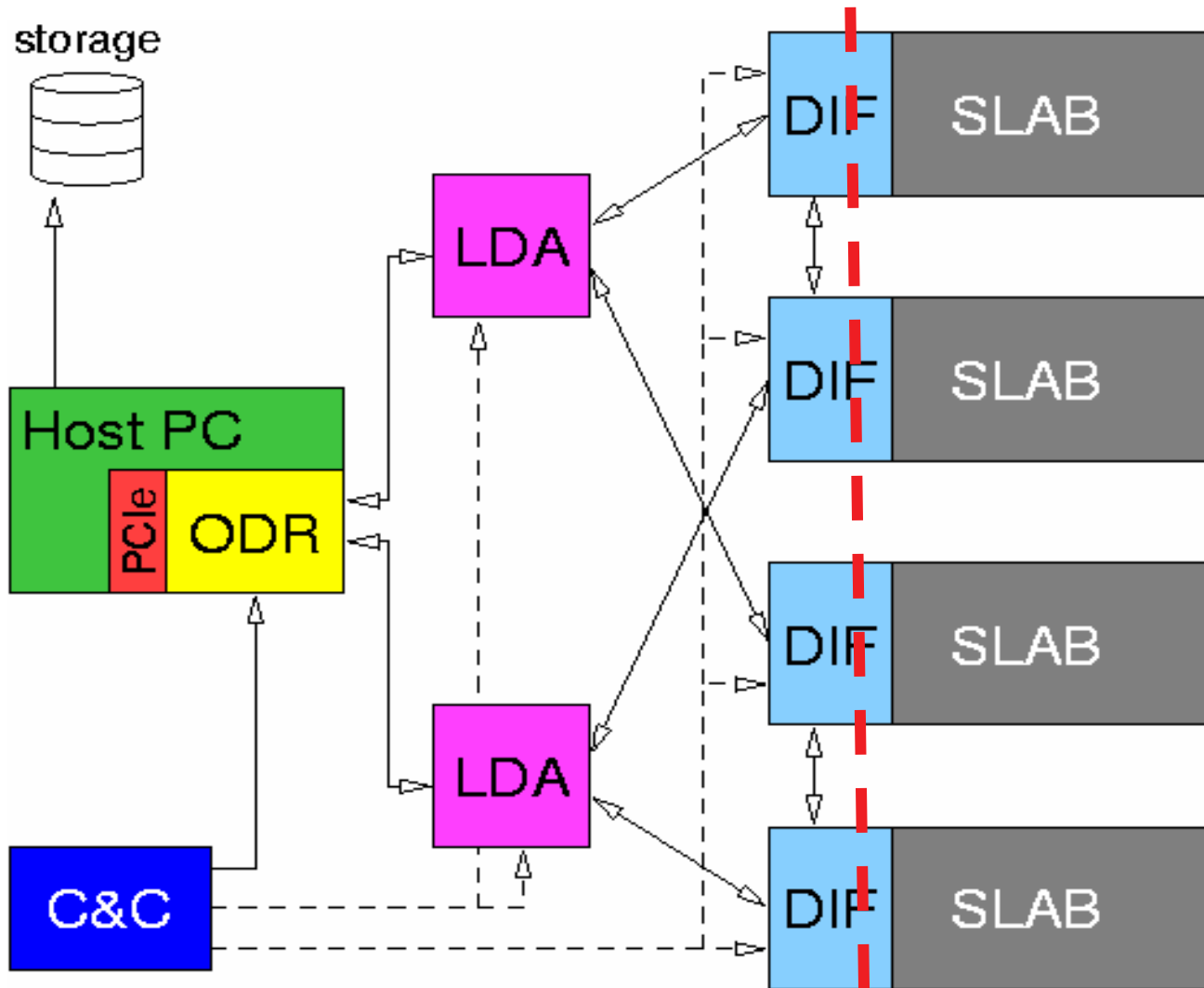
# DIF Functionality

- Receive, regenerate and distribute clocks
- Receive, buffer, package and send data from VFE to LDA
- Receive and decode incoming commands and issue corresponding signals
- Control the DIF-DIF redundancy connection
- Receive, decode and distribute slow control commands
- Control power pulsing and provide watchdog functionality
- Provide an USB interface for stand-alone running and debugging
- .....on top of that: all the things we did not think of so far

# DIF implementation

- The Slab is an integral part of the detector
- The LDA and ODR are transparent wrt detector type
- The DIF and its interface to the slab is detector-specific
- Large parts of the DIF firmware *can/should/must* be generalised
- *DIF hardware should support firmware* to profit from common developments
- DIF working group to address common problems and share knowledge, experience, and VHDL code
- DIF wg: representatives of detectors + UK-DAQ person

# Opportunity to memorise the acronyms:

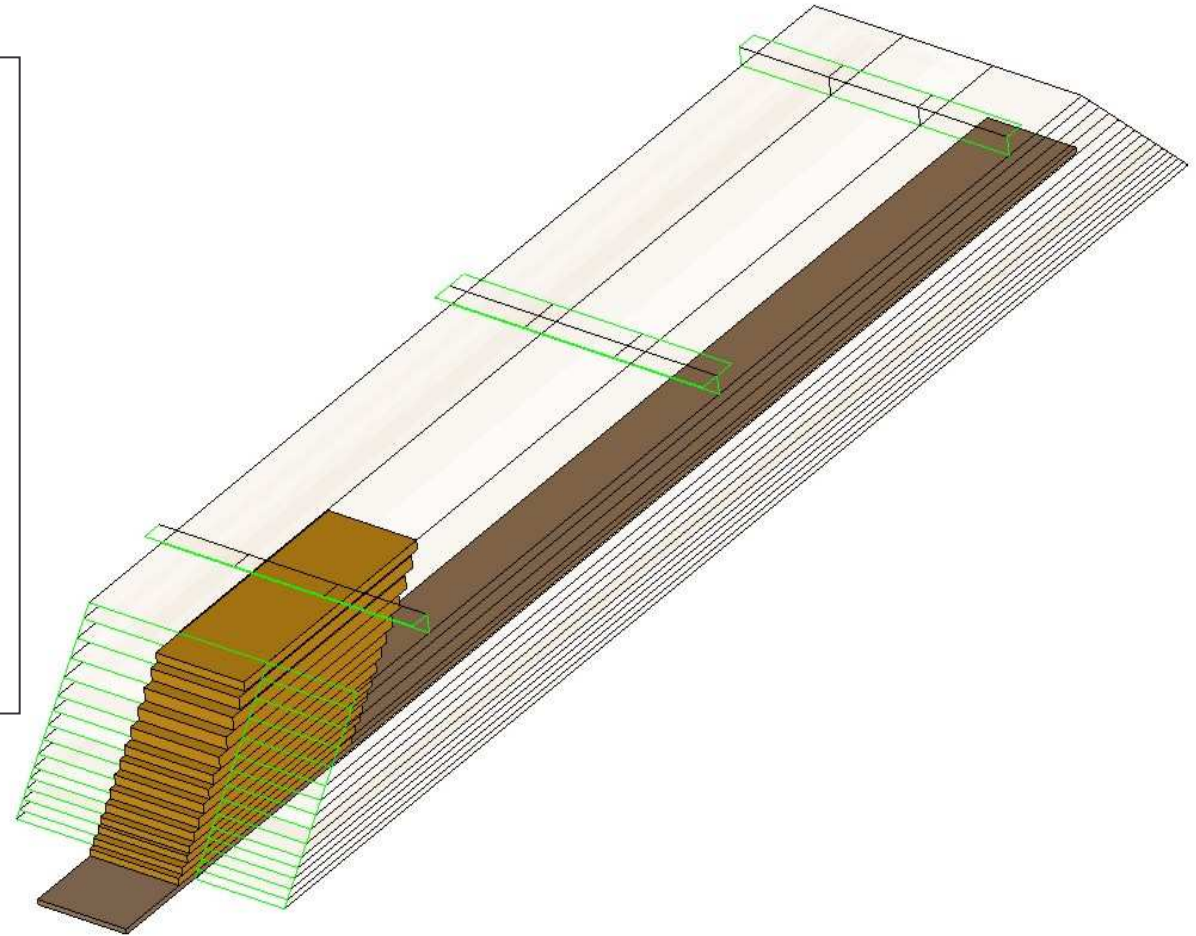


- DIF: Detector InterFace
- LDA: Link/Data Aggregator
- ODR: Off-Detector Receiver
- C&C: Clock & Controls
- PCIe: PCI-Express

**UK efforts**

# The EUDET prototype

- Full stack: 15 slabs, instrumented on both sides
- As close to CALICE technology as reasonably possible



# Prototype development

NOW

2008

2009

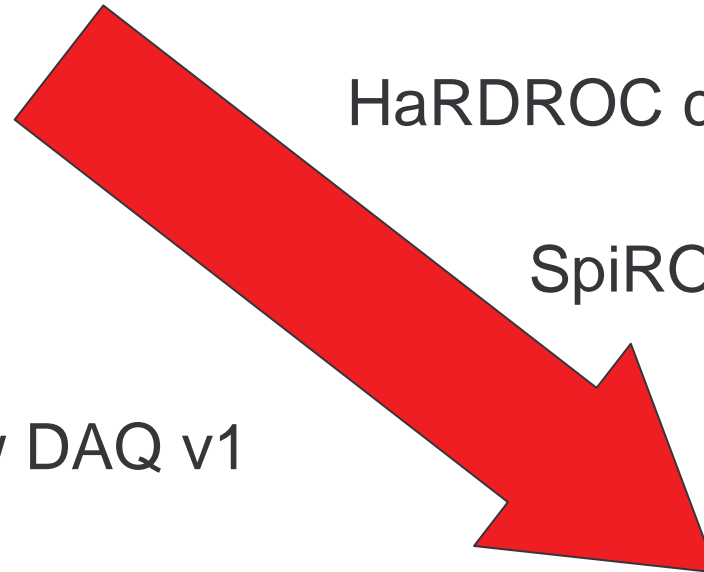
HaRDROC chip v1  
Testbeam DAQ

HaRDROC chip v2

SpiROC/SkiROC chip v1

New DAQ v1

EUDET proto:  
detector + DAQ



# Technology prototype for physics results

EUDET module is quite a large and complex object.

Keep future mass production in mind:

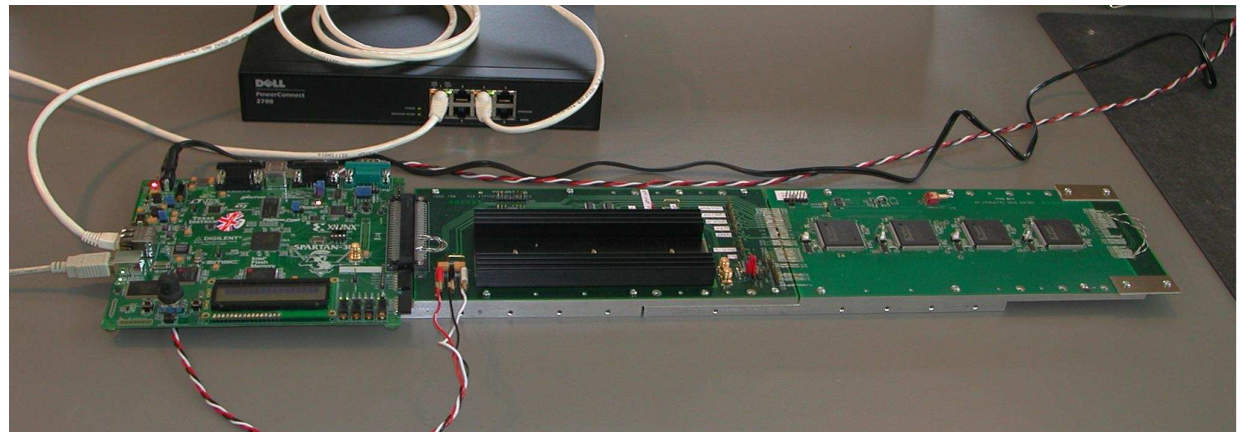
- large objects are assemblies of smaller objects
- develop testable objects

Many technology options require even more R&D:

- power consumption
- data rate: speed vs. power
- noise
- etc.

# R&D for the EUDET prototype

- Proto-slab:
  - FPGA for VFES
  - provisional 'DIF' for ECAL

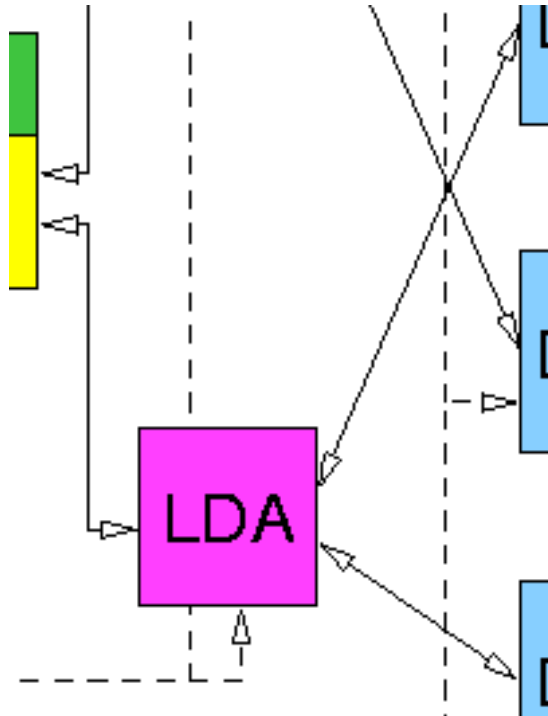


- Tests of signal distribution along long PCB lines: signal deterioration, termination options, speed, etc.
- Identification of possible issues with many (pseudo)VFE chips on long transmission paths
- Familiarise ourselves with VFE readout architecture



# R&D for the EUDET prototype

More to come.....



...but let's look at the LDA design first